

Board Level Cooling – Bond On 2292



BOARD LEVEL COOLING – Bond On 2292

Bond On 2292 is a circular board level heat sink designed to cool Leadless Chip Carriers, Flat Packs, and 68 position devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
2292BG	Leadless Chip Carriers, Flat Packs and 68 position



HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Epoxy
Thermal Interface Material	Epoxy

Property	Details
Heat Sink Width (mm)	28.58
Heat Sink Length (mm)	28.58
Heat Sink Height (mm)	9.14
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

